

**Amendments to the Claims:**

Claims 1, 3, and 5 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1. (Currently Amended) A method of enhancing adhesion of a compound to a surface of a substrate comprising:

providing the substrate having the surface;

finding irregularities to remove from the substrate by scanning the substrate to locate irregularities for irregularities for removal; and

roughening the surface of the substrate when removing ~~for removal of~~ irregularities.

2. (Previously Presented) The method according to claim 1, wherein roughening comprises removing contamination and foreign particles from the surface of the substrate.

3. (Currently Amended) A method of enhancing adhesion of a material to a surface of a substrate comprising:

providing the substrate having the surface;

determining irregularities to remove from the substrate by scanning the substrate for irregularities for removal; and

roughening the surface of the substrate while removing irregularities.

4. (Previously Presented) The method according to claim 3, wherein roughening comprises removing contamination and foreign particles from the surface of the substrate.

5. (Currently Amended) A method for improving adhesion of a compound to a surface of a substrate comprising:  
providing the substrate having the surface;  
locating irregularities to be removed from the substrate by scanning the substrate for irregularities  
~~for removal~~; and  
roughening the surface of the substrate while removing irregularities from the substrate.

6. (Previously Presented) The method according to claim 5, wherein roughening comprises removing contamination and foreign particles from the surface of the substrate.